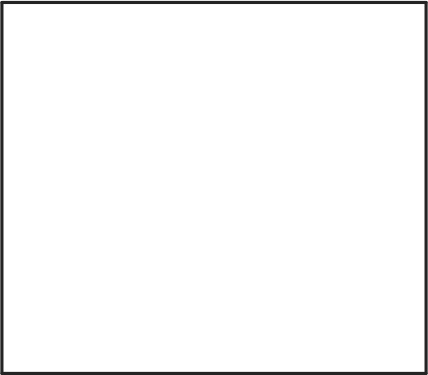


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP20487	REV: A	SUN REV: Not In VersionControl
	TID #: N/A		
PLOT NAME = Top Assembly Drawing	GENERATED : 9/9/2016	9:53:39 AM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP20487	REV: A	SUN REV: Not In VersionControl
	TID #: N/A		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 9/9/2016 9:53:41 AM		TEXAS INSTRUMENTS

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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